

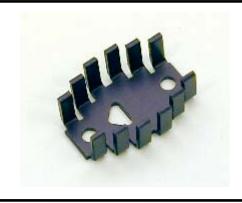
Technical Data

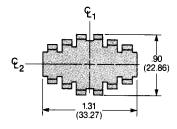
METAL CASE, CASE-MOUNTED SEMICONDUCTORS

Part Number Series LA-A2

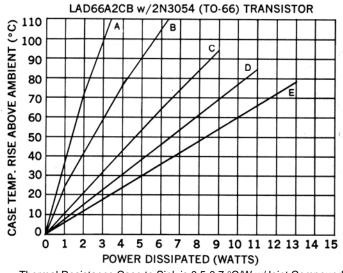
Natural Conv. (°C/W): 19.7 Forced Air (°C/W): 6.4

Mounting Envelope: 1.31" x .90" x .25"









DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.E. 1000 FPM w/Diss.

- \bullet $\;$ Thermal Resistance Case to Sink is 0.5-0.7 °C/W w/Joint Compound.
- Derate 0.4 °C/watt for unplated part in natural convection only.

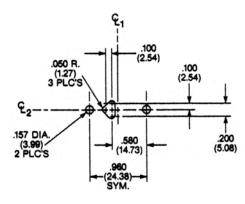
Ordering Information

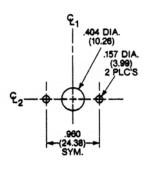
CTS IERC PART NO.			Semiconductor	Hole patt. ref.	Max. Weight
Unplated	Comm'l. Black	Mil. Black	Accommodated	no.	(Grams)
	Anodize	Anodize			
LA000A2U	LA000A2CB	LA000A2B	Undrilled		4.6
LAD66A2U	LAD66A2CB	LAD66A2B	TO-66	1 (see below)	4.6
LAIC66A2U	LAIC66A2CB	LAIC66A2B	TO-66 IC	7 (see below)	4.6

HOLE PATTERNS

1. Hole Pattern no. 248 accommodates TO-66s. Available in LA-A, LA-B and LB series heat dissipators only.

7. Hole pattern no. 191 accommodates To-66 lcs. Available in LA-A, LA-B, and LB series heat dissipators only.





CTS IERC, Heat Sinks and Thermal Management Solutions

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